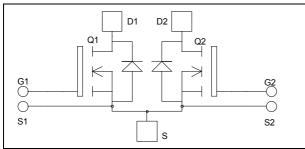


Dual common source **MOSFET Power Module**

$$V_{DSS} = 200V$$

$$R_{DSon} = 4m\Omega \text{ typ } @ \text{Tj} = 25^{\circ}\text{C}$$

$$I_D = 372\text{A} @ \text{Tc} = 25^{\circ}\text{C}$$



Application

- AC Switches
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] MOSFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
 - High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- **RoHS** Compliant

Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
$V_{ m DSS}$	Drain - Source Breakdown Voltage		200	V
Ţ	Continuous Drain Current	$T_c = 25^{\circ}C$	372	
I_D	Continuous Drain Current	$T_c = 80$ °C	278	A
I_{DM}	Pulsed Drain current		1488	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		5	mΩ
P_D	Maximum Power Dissipation	$T_c = 25^{\circ}C$	1250	W
I_{AR}	Avalanche current (repetitive and non repetitive)		100	A
E _{AR}	Repetitive Avalanche Energy		50	mJ
E_{AS}	Single Pulse Avalanche Energy		3000	1113

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 200V$	$T_j = 25^{\circ}C$			500	^	
		$V_{GS} = 0V, V_{DS} = 160V$	$T_{j} = 125^{\circ}C$			2000	μΑ	
R _{DS(on)}	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 186A$			4	5	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 10$ mA		3		5	V	
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{V}$				±200	nA	

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		28.9		
C_{oss}	Output Capacitance	$V_{DS} = 25V$		9.32		nF
C_{rss}	Reverse Transfer Capacitance	f = 1MHz		0.58		
Q_{g}	Total gate Charge	$V_{GS} = 10V$		560		
Q_{gs}	Gate – Source Charge	$V_{Bus} = 100V$		212		пC
Q_{gd}	Gate – Drain Charge	$I_D = 372A$		268		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C		32		
$T_{\rm r}$	Rise Time	$V_{GS} = 15V$		64		ns
$T_{d(off)}$	Turn-off Delay Time	$V_{\text{Bus}} = 133V$ $I_{\text{D}} = 372A$		88		
T_{f}	Fall Time	$R_G = 1.2\Omega$		116		
Eon	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15V$, $V_{Bus} = 133V$ $I_D = 372A$, $R_G = 1.2\Omega$		3396		1
E _{off}	Turn-off Switching Energy			3716		μJ
Eon	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 372A, R_G = 1.2\Omega$		3744		
E_{off}	Turn-off Switching Energy			3944		μJ

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_S	Continuous Source current		$Tc = 25^{\circ}C$			372	Α
	(Body diode)		$Tc = 80^{\circ}C$			278	Λ
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = -372$	A			1.3	V
dv/dt	Peak Diode Recovery 1					5	V/ns
t_{rr}	Reverse Recovery Time	$I_S = -372A, V_R = 133V$			360		ns
Q_{rr}	Reverse Recovery Charge	$di_S/dt = 400A/\mu s$			26.8		μС

• dv/dt numbers reflect the limitations of the circuit rather than the device itself.

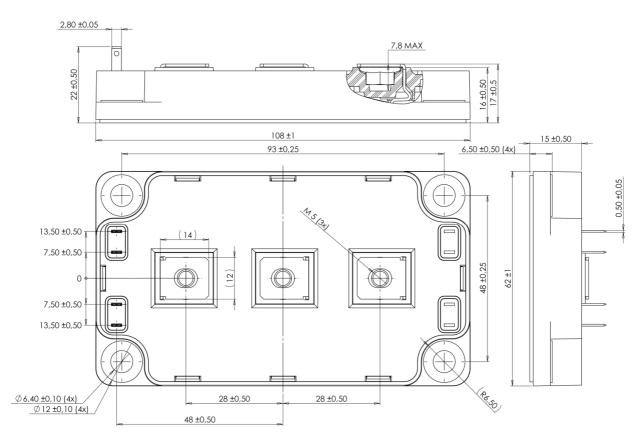
 $I_S \leq \text{- }372A \qquad \text{di/dt} \leq 700 \text{A/}\mu\text{s} \qquad V_R \leq V_{DSS} \qquad T_j \leq 150 ^{\circ}\text{C}$



Thermal and package characteristics

Symbol	Characteristic		Min	Тур	Max	Unit	
R_{thJC}	Junction to Case Thermal Resistance					0.1	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range		-40		150	°C	
T_{STG}	Storage Temperature Range			-40			125
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	11.111
Wt	Package Weight					300	g

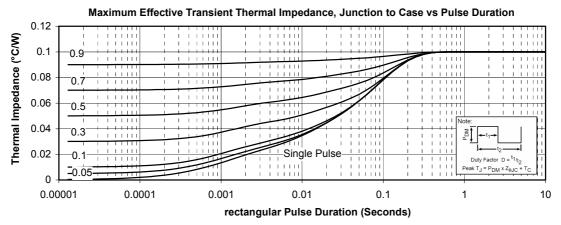
SP6 Package outline (dimensions in mm)

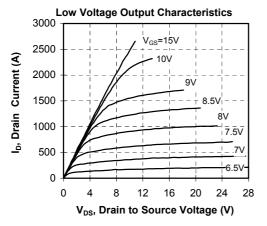


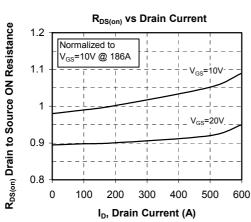
 $See \ application \ note \ APT0601 - Mounting \ Instructions \ for \ SP6 \ Power \ Modules \ on \ www.microsemi.com$

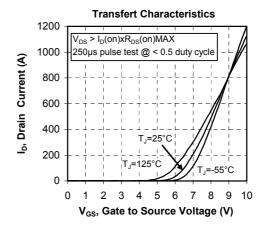


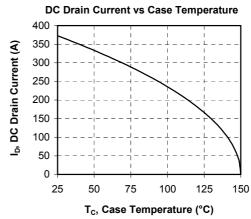
Typical Performance Curve



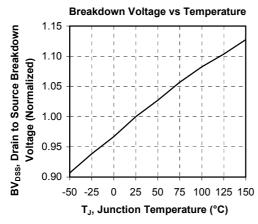












Threshold Voltage vs Temperature

1.2

1.1

1.0

0.9

8.0

0.7

0.6

100000

10000

1000

100

0

10

V_{DS}, Drain to Source Voltage (V)

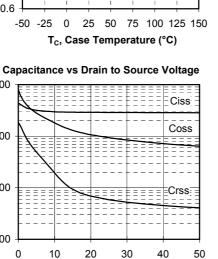
C, Capacitance (pF)

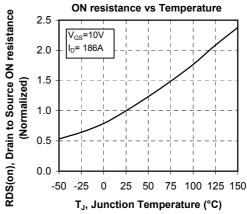
-50 -25

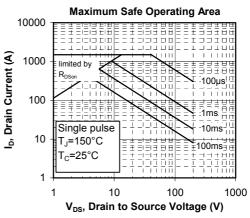
V_{GS}(TH), Threshold Voltage

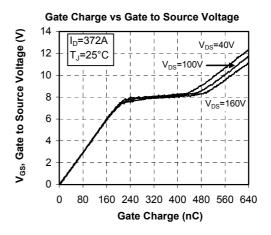
(Normalized)



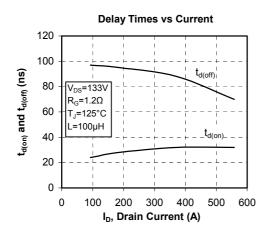


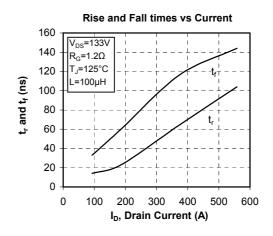


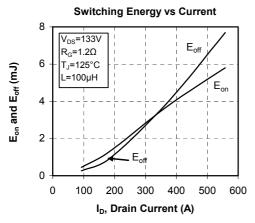


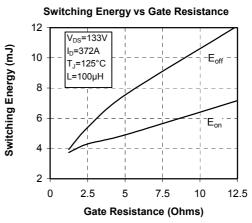


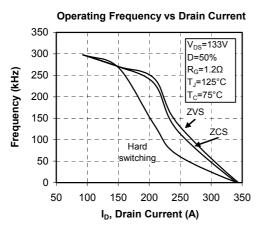


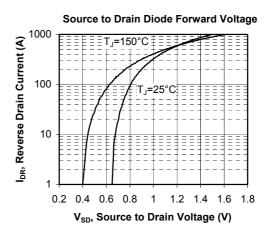














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